Amendments to the Claims:

The following listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (currently amended) A method of manufacturing a transparent substrate that is to have a transparent conductive film formed on a surface thereof, comprising:

controlling a surface smoothness of the surface of the transparent substrate to satisfy $0 \text{ nm} \leq Rz \leq 4 \text{ nm}$; and

controlling a surface smoothness of a surface of the transparent conductive film to satisfy $0 \text{ nm} \leq Rz \leq 8 \text{ nm}$[[,]]

~~wherein the controlling of the surface smoothness is carried out by omitting polishing of the surface of the transparent substrate~~.

2. (canceled)

3. (currently amended) The method of manufacturing a transparent substrate as claimed in claim [[1]] 31, wherein the surface of the transparent substrate is subjected to etching using an acidic aqueous solution containing hydrofluoric acid or an alkaline aqueous solution containing potassium hydroxide or sodium hydroxide.

4. (previously presented) The method of manufacturing a transparent substrate as claimed in claim 3, wherein after the etching has been carried out, the surface of the transparent substrate is subjected to alkaline washing comprising washing using an alkaline liquid.

5.-13 (canceled)

14.-30. (canceled)

31. (new) The method of manufacturing a transparent substrate as claimed in claim 1, wherein the controlling of the surface smoothness is carried out by omitting polishing of the surface of the transparent substrate.

32. (new) The method of manufacturing a transparent substrate as claimed in claim 1, wherein the controlling of the surface smoothness is carried out mainly by polishing the surface of the transparent substrate.

33. (new) The method of manufacturing a transparent substrate as claimed in claim 32, wherein the polishing of the surface of the transparent substrate is carried out using a cerium oxide powder having a predetermined mean particle diameter, and after the polishing of the surface of the transparent substrate has been carried out, the surface of the transparent substrate is washed using a mixed liquid of sulfuric acid and ascorbic acid or a mixed liquid of nitric acid and ascorbic acid, and after the surface of the transparent substrate has been washed, the surface of the transparent substrate is subjected to etching using an acidic aqueous solution containing

hydrofluoric acid or an alkaline aqueous solution containing potassium hydroxide or sodium hydroxide.

34. (new) The method of manufacturing a transparent substrate as claimed in claim 33, wherein after the etching has been carried out, the surface of the transparent substrate is subjected to alkaline washing comprising washing using an alkaline liquid.

35. (new) The method of manufacturing a transparent substrate as claimed in claim 32, wherein the polishing of the surface of the transparent substrate is carried out using a cerium oxide powder having a predetermined mean particle diameter, and is then further carried out using a cerium oxide powder having a mean particle diameter lower than the predetermined mean particle diameter.

36. (new) The method of manufacturing a transparent substrate as claimed in claim 35, wherein after the polishing of the surface of the transparent substrate has been carried out, the surface of the transparent substrate is washed using a mixed liquid of sulfuric acid and ascorbic acid or a mixed liquid of nitric acid and ascorbic acid.

37. (new) The method of manufacturing a transparent substrate as claimed in claim 36, wherein after the surface of the transparent substrate has been washed, the surface of the transparent substrate is subjected to alkaline washing comprising washing using an alkaline liquid.

38. (new) The method of manufacturing a transparent substrate as claimed in claim 36, wherein after the surface of the transparent substrate has been washed, the surface of the transparent substrate is subjected to etching using an acidic aqueous solution containing hydrofluoric acid or an alkaline aqueous solution containing potassium hydroxide or sodium hydroxide.

39. (new) The method of manufacturing a transparent substrate as claimed in claim 35, wherein after the polishing of the surface of the transparent substrate has been carried out, the surface of the transparent substrate is subjected to etching using an acidic aqueous solution containing hydrofluoric acid or an alkaline aqueous solution containing potassium hydroxide or sodium hydroxide.

40. (new) The method of manufacturing a transparent substrate as claimed in claim 38, wherein after the etching has been carried out, the surface of the transparent substrate is subjected to alkaline washing comprising washing using an alkaline liquid.